onsemi

3.3 V ECL ÷2 Divider MC100LVEL32

Description

The MC100LVEL32 is an integrated \div 2 divider. The LVEL32 is functionally identical to the EL32, but operates from a 3.3 V supply.

The reset pin is asynchronous and is asserted on the rising edge. Upon power-up, the internal flip-flop will attain a random state; the reset allows for the synchronization of multiple LVEL32's in a system.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 µF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

Features

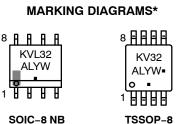
- 510 ps Propagation Delay
- 2.6 GHz Typical Maximum Frequency
- ESD Protection:
 - ♦ > 4 KV Human Body Model
 - ◆ > 200 V Machine Model
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range: V_{CC} = 3.0 V to 3.8 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = -3.0 V to -3.8 V
- Internal Input Pulldown Resistors
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity:
 - ♦ Level 1 for SOIC-8
 - ◆ Level 3 for TSSOP-8
 - For Additional Information, see Application Note <u>AND8003/D</u>
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 111 Devices
- These Devices are Pb-Free, Halogen Free and are RoHS Compliant





SOIC-8 NB D SUFFIX CASE 751-07

TSSOP-8 DT SUFFIX CASE 948R-02



A = Assembly Location L = Wafer Lot Y = Year W = Work Week

= Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note <u>AND8002/D</u>.

ORDERING INFORMATION

Device	Package	Shipping [†]
MC100LVEL32DG	SOIC-8 NB (Pb-Free)	98 Units / Tube
MC100LVEL32DR2G	SOIC-8 NB (Pb-Free)	2,500 / Tape & Reel
MC100LVEL32DTR2G	TSSOP-8 (Pb-Free)	2,500 / Tape & Reel

DISCONTINUED (Note 1)

MC100LVEL32DTG	TSSOP-8	100 Units / Tube
	(Pb-Free)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, <u>BRD8011/D</u>.

1. **DISCONTINUED:** This device is not recommended for new design. Please contact your **onsemi** representative for information. The most current information on this device may be available on <u>www.onsemi.com</u>.

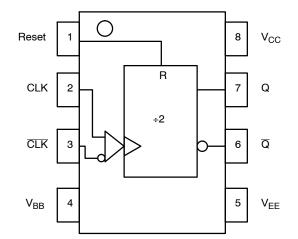


Figure 1. Logic Diagram and Pinout Assessment

Table 2. MAXIMUM RATINGS

Table 1. PIN DESCRIPTION

Pin	Function
CLK*, CLK**	ECL Differential Clock Inputs
Q, <u>Q</u>	ECL Differential Data ÷2 Outputs
Reset*	ECL Asynch Reset
V _{BB}	Reference Voltage Output
V _{CC}	Positive Supply
V _{EE}	Negative Supply

*Pin will default low when left open, per internal 75 K pull-down to

 $V_{EE}.$ ** Pin will default to $V_{CC}/2$ when left open per internal 75 K Ω pull-down to V_{EE} and 75 K Ω pull-up to $V_{CC}.$

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		8 to 0	V
V_{EE}	NECL Mode Power Supply	$V_{CC} = 0 V$		-8 to 0	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$V_{I} \leq V_{CC} \\ V_{I} \geq V_{EE}$	6 to 0 -6 to 0	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$V_{I} \leq V_{CC} \\ V_{I} \geq V_{EE}$	6 to 0 -6 to 0	V
l _{out}	Output Current	Continuous Surge		50 100	mA
I _{BB}	V _{BB} Sink/Source			±0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 NB SOIC-8 NB	190 130	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8 NB	41 to 44 ±5%	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44 ±5%	°C/W
T _{sol}	Wave Solder (Pb-Free)	< 2 to 3 sec @ 260°C		265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

2. JEDEC standard multilayer board - 2S2P (2 signal, 2 power)

		−40°C		25°C		85°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		29	35		29	35		31	36	mA
V _{OH}	Output HIGH Voltage (Note 2)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V _{OL}	Output LOW Voltage (Note 2)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
VIH	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
VIL	Input LOW Voltage (Single-Ended)	1490		1825	1490		1825	1490		1825	mV
V_{BB}	Output Voltage Reference	1.92		2.04	1.92		2.04	1.92		2.04	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3) V _{PP} < 500 mV V _{PP} ≥ 500 mV	1.2 1.4		3.1 3.1	1.1 1.3		3.1 3.1	1.1 1.3		3.1 3.1	V
I _{IH}	Input HIGH Current			150			150			150	μA
I _{IL}	Input LOW Current CLK CLK	0.5 -600			0.5 -600			0.5 -600			μΑ

Table 3. LVPECL DC CHARACTERISTICS (V_{CC} = 3.3 V; V_{EE} = 0.0 V (Note 1))

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

1. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.

Outputs are terminated through a 50 Ω resistor to V_{CC} – 2.0 V.
 V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1 V.

		–40°C		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		29	35		29	35		31	36	mA
V _{OH}	Output HIGH Voltage (Note 2)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V _{OL}	Output LOW Voltage (Note 2)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V _{IL}	Input LOW Voltage (Single-Ended)	-1810		-1475	-1810		-1475	-1810		-1475	mV
V _{BB}	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3) V _{PP} < 500 mV V _{PP} ≥ 500 mV	-2.1 -1.9		-0.2 -0.2	-2.1 -1.9		-0.2 -0.2	-2.1 -1.9		-0.2 -0.2	V
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current CLK CLK	0.5 -600			0.5 -600			0.5 -600			μΑ

Table 4. LVNECL DC CHARACTERISTICS (V_{CC} = 0.0 V; V_{EE} = -3.3 V (Note 1))

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary ±0.3 V.
 Outputs are terminated through a 50 Ω resistor to V_{CC} – 2.0 V.
 V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1 V.

			–40°C 25°C			85°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency	2.2	2.5		2.4	2.6		2.6	2.8		GHz
t _{PLH} t _{PHL}	Propagation Delay CLK to Q (Differen- tial) CLK to Q (Single-Ended) Reset to Q	350 300 440	500 500 555	530 580 640	370 320 450	510 510 540	550 600 650	410 360 480	540 540 580	590 640 680	ps
t _{RR}	Reset Recovery	175	50		175	50		175	50		ps
t _{PW}	Minimum Pulse Width Reset	500	300		500	300		500	300		ps
t _{JITTER}	Random Clock Jitter (RMS)		2.0			2.0			2.0		ps
V _{PP}	Input Swing (Differential Swing) (Note 2)	150		1000	150		1000	150		1000	mV
t _r t _f	Output Rise / Fall Times Q (20%-80%)	120	225	320	120	225	320	120	225	320	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

V_{EE} can vary ±0.3 V.
 V_{PP}(min) is input swing measured single-ended on each input in differential configuration.

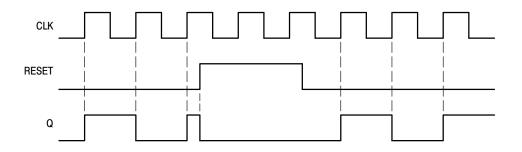


Figure 1. Timing Diagram

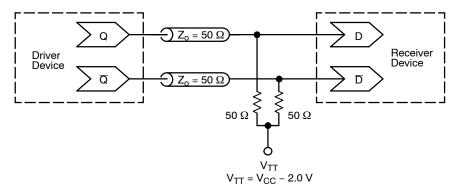


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D - Termination of ECL Logic Devices)

Resource Reference of Application Notes

- AN1405/D ECL Clock Distribution Techniques
 AN1406/D Designing with PECL (ECL at +5.0 V)
 AN1503/D ECLinPS I/O SPiCE Modeling Kit
 AN1504/D Metastability and the ECLinPS Family
 AN1568/D Interfacing Between LVDS and ECL
 AN1672/D The ECL Translator Guide
- AND8001/D Odd Number Counters Design
- AND8002/D Marking and Date Codes
- AND8020/D Termination of ECL Logic Devices
- AND8066/D Interfacing with ECLinPS
- AND8090/D AC Characteristics of ECL Devices

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*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

STYLES ON PAGE 2

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SOIC-8 NB CASE 751-07 ISSUE AK

STYLE 1: PIN 1. EMITTER COLLECTOR 2. COLLECTOR 3. 4. EMITTER 5. EMITTER BASE 6. 7 BASE EMITTER 8. STYLE 5: PIN 1. DRAIN 2. DRAIN З. DRAIN DRAIN 4. GATE 5. 6. GATE SOURCE 7. 8. SOURCE STYLE 9: PIN 1. EMITTER, COMMON COLLECTOR, DIE #1 COLLECTOR, DIE #2 2. З. EMITTER, COMMON 4. 5. EMITTER, COMMON 6 BASE. DIE #2 BASE, DIE #1 7. 8. EMITTER, COMMON STYLE 13: PIN 1. N.C. 2. SOURCE 3 GATE 4. 5. DRAIN 6. DRAIN DRAIN 7. 8. DRAIN STYLE 17: PIN 1. VCC 2. V2OUT V10UT З. TXE 4. 5. RXE 6. VFF 7. GND 8. ACC STYLE 21: PIN 1. CATHODE 1 2. CATHODE 2 3 CATHODE 3 CATHODE 4 4. 5. CATHODE 5 6. COMMON ANODE COMMON ANODE 7. 8. CATHODE 6 STYLE 25: PIN 1. VIN 2 N/C REXT З. 4. GND 5. IOUT 6. IOUT IOUT 7. 8. IOUT STYLE 29: BASE, DIE #1 PIN 1. 2 EMITTER, #1 BASE, #2 З. EMITTER, #2 4. 5 COLLECTOR, #2 COLLECTOR, #2 6.

STYLE 2: PIN 1. COLLECTOR, DIE, #1 2. COLLECTOR, #1 COLLECTOR, #2 3. 4 COLLECTOR, #2 BASE, #2 5. EMITTER, #2 6. 7 BASE #1 EMITTER, #1 8. STYLE 6: PIN 1. SOURCE 2. DRAIN 3. DRAIN SOURCE 4. SOURCE 5. 6. GATE GATE 7. 8. SOURCE STYLE 10: GROUND PIN 1. BIAS 1 OUTPUT 2. З. GROUND 4. 5. GROUND 6 BIAS 2 INPUT 7. 8. GROUND STYLE 14: PIN 1. N-SOURCE 2. N-GATE 3 P-SOURCE P-GATE 4. P-DRAIN 5 6. P-DRAIN N-DRAIN 7. N-DRAIN 8. STYLE 18: PIN 1. ANODE ANODE 2. SOURCE 3. GATE 4. 5. DRAIN 6 DRAIN CATHODE 7. 8. CATHODE STYLE 22: PIN 1. I/O LINE 1 2. COMMON CATHODE/VCC 3 COMMON CATHODE/VCC 4. I/O LINE 3 COMMON ANODE/GND 5. 6. I/O LINE 4 7. I/O LINE 5 8. COMMON ANODE/GND STYLE 26: PIN 1. GND 2 dv/dt З. ENABLE 4. ILIMIT 5. SOURCE SOURCE 6. SOURCE 7. 8. VCC STYLE 30: DRAIN 1 PIN 1. DRAIN 1 2 GATE 2 З. SOURCE 2 4. SOURCE 1/DRAIN 2 SOURCE 1/DRAIN 2 5. 6.

STYLE 3: PIN 1. DRAIN, DIE #1 DRAIN, #1 2. DRAIN, #2 З. DRAIN, #2 4. GATE, #2 5. SOURCE, #2 6. 7 GATE #1 8. SOURCE, #1 STYLE 7: PIN 1. INPUT 2. EXTERNAL BYPASS THIRD STAGE SOURCE GROUND З. 4. 5. DRAIN 6. GATE 3 SECOND STAGE Vd 7. FIRST STAGE Vd 8. STYLE 11: PIN 1. SOURCE 1 GATE 1 SOURCE 2 2. 3. GATE 2 4. 5. DRAIN 2 6. DRAIN 2 DRAIN 1 7. 8. DRAIN 1 STYLE 15: PIN 1. ANODE 1 2. ANODE 1 ANODE 1 3 ANODE 1 4. 5. CATHODE, COMMON CATHODE, COMMON CATHODE, COMMON 6. 7. CATHODE, COMMON 8. STYLE 19: PIN 1. SOURCE 1 GATE 1 SOURCE 2 2. 3. GATE 2 4. 5. DRAIN 2 6. MIRROR 2 7. DRAIN 1 8. **MIRROR 1** STYLE 23: PIN 1. LINE 1 IN COMMON ANODE/GND COMMON ANODE/GND 2. 3 LINE 2 IN 4. LINE 2 OUT 5. COMMON ANODE/GND COMMON ANODE/GND 6. 7. 8. LINE 1 OUT STYLE 27: PIN 1. ILIMIT 2 OVI 0 UVLO З. 4. INPUT+ 5. 6. SOURCE SOURCE SOURCE 7. 8 DRAIN

STYLE 4: PIN 1. 2. ANODE ANODE ANODE З. 4. ANODE ANODE 5. 6. ANODE 7 ANODE COMMON CATHODE 8. STYLE 8: PIN 1. COLLECTOR, DIE #1 2. BASE, #1 BASE #2 З. COLLECTOR, #2 4. COLLECTOR, #2 5. 6. EMITTER, #2 EMITTER, #1 7. 8. COLLECTOR, #1 STYLE 12: PIN 1. SOURCE SOURCE 2. 3. GATE 4. 5. DRAIN 6. DRAIN DRAIN 7. 8. DRAIN STYLE 16 EMITTER, DIE #1 PIN 1. 2. BASE, DIE #1 EMITTER, DIE #2 3 BASE, DIE #2 4. 5. COLLECTOR, DIE #2 6. COLLECTOR, DIE #2 COLLECTOR, DIE #1 7. COLLECTOR, DIE #1 8. STYLE 20: PIN 1. SOURCE (N) GATE (N) SOURCE (P) 2. 3. 4. GATE (P) 5. DRAIN 6. DRAIN DRAIN 7. 8. DRAIN STYLE 24: PIN 1. BASE EMITTER 2. 3 COLLECTOR/ANODE COLLECTOR/ANODE 4. 5. CATHODE

6. CATHODE COLLECTOR/ANODE 7. 8. COLLECTOR/ANODE STYLE 28: PIN 1. SW_TO_GND 2. DASIC OFF DASIC_SW_DET З. 4. GND 5. 6. V MON VBULK 7. VBULK

7. VOULK 8. VIN

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SOURCE 1/DRAIN 2

7.

8. GATE 1

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7.

8

COLLECTOR, #1

COLLECTOR, #1

semi

-T- SEATING

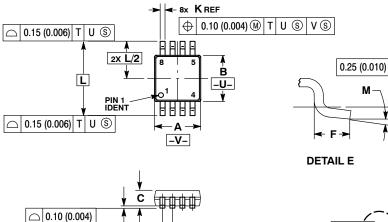
PLANE

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TSSOP-8 3.00x3.00x0.95 CASE 948R-02 ISSUE A

DATE 07 APR 2000



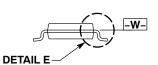
0.25 (0.010)

NOTES:

4.

5.

PER SIDE.



	MILLIN	IETERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	2.90	3.10	0.114	0.122		
В	2.90	3.10	0.114	0.122		
С	0.80	1.10	0.031	0.043		
D	0.05	0.15	0.002	0.006		
F	0.40	0.70	0.016	0.028		
G	0.65	BSC	0.026 BSC			
K	0.25	0.40	0.010	0.016		
L	4.90	4.90 BSC		BSC		
М	0°	6 °	0 °	6 °		

NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER. 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE. 4. DIMENSION B DOES NOT INCLUDE INTERLED

FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010)

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